



SLA580 Serise

Through-hole LEDs

Visual light emitting diodes does not contain reinforcement materials such as glass fillers. Therefore if sudden thermal and mechanical shock are given, destruction or inferiority of luminous intensity may occur. Please take care of the handling.

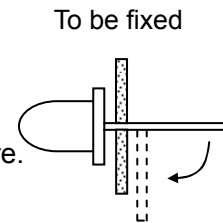
■FIXATION METHOD

1.ATTENTION POINTS

- 1-1) Please do not give excessive heat over storage temperature to resin.
However, In case that the product has to be heated in oven for the glue fixing, it can stand under (125°C MAX, 120sec MAX) condition.
- 1-2) Please avoid stress to resin at high temperature.

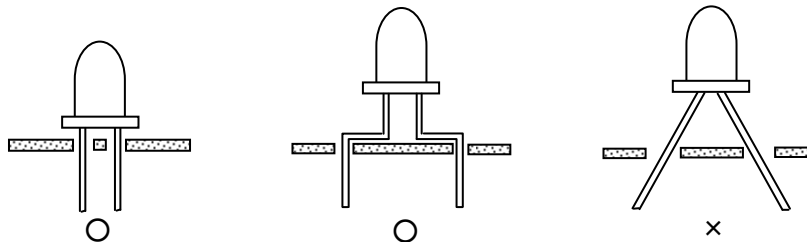
2.TERMINATION PROCESSING

- 2-1) In case of termination processing, please fix the termination processing position, and process before reverse side of LED body. Please process before soldering. If stress is given during processing, It may cause non-lighting failure.



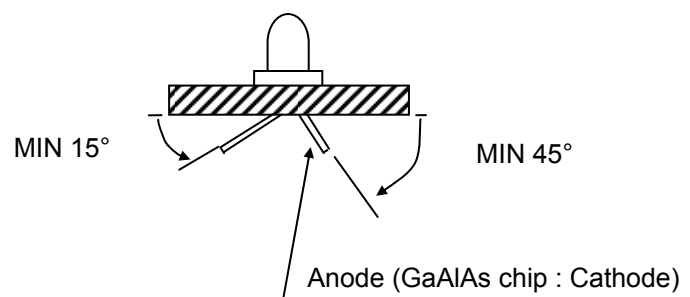
3.ASSEMBLY ON PC BOARD

- 3-1) In case of soldering on PCB, if the operation is done with stress, it may cause non-lighting failure during soldering or using.



- 3-2) Therefore please design holes of PCB suitable for termination space or termination space after forming, and avoid the stress.

Especially in case of clinch to PCB, please do not leave remained stress.
Enough evaluation is requested before deciding assembly conditions.
Please consult with us if any problems emerged in the evaluation stage.





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4.SOLDERING (Sn-3Ag-0.5Cu)

- 4-1) Please make soldering rapidly under the following temperature and time conditions.
 4-2) Please avoid stress to LED lamp during soldering.
 4-3) Recommendable soldering conditions are as follows :

ARTIICLE		SOLDERING TEMP	OPERATION TIME
Soldering Dip	Preheat	Max. 100°C	Max. 60sec
	Soldering Bath	Max. 265°C	Max. 5sec
Soldering Iron		Max. 400°C	Max. 3sec

5.CLEANING

- 5-1) In case of cleaning, some solvents may cause damage of resin or cause non-lighting failure, so please check the solvent before actual use.
 The recommendable cleaning solvent is alcoholic one such as isopropyl alcohol.

RECOMMENDABLE CLEANING CONDITIONS

METHOD	CONDITIONS
Cleaning by solvent	Temperature of solvent : Max. 45°C Immersion time : Max. 3min
Cleaning by ultrasonic	Ultrasonic out : Max. 15W/Liter Cleaning time : Max. 3min

■ATTENTION ON STORAGING

Storage in dry box is most desirable, but if it is not possible, we recommend following conditions.

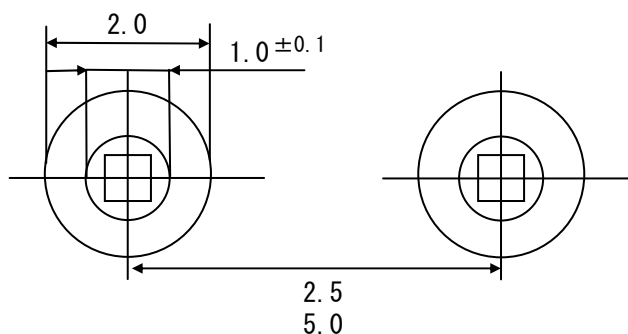
Temperature : 5 ~ 30°C

Humidity : Max. 60%

■RECOMMENDABLE ROUND PATTERN

Round pattern depends on the material PCB, density and circuit arrangement.

Our recommendation is as follow :



* Unit : mm

* Lead types : □0.5mm